Procedural Review Voting Sheet
2012 Cycle 5

REGION: Japan
COMMITTEE: Silicon Wafer
EVENT: SEMICON Japan 2012
DATE OF MEETING: Dec. 6, 2012
PLACE OF MEETING: Makuhari Messe, Chiba, Japan
COMMITTEE CO-CHAIRS: Naoyuki J. Kawai/The University of Tokyo, Tetsuya Nakai/SUMCO
SEMI STAFF: Hirofumi Kanno

A&R Voter: Name/Company
Date: 200X/MM/DD

I. Document Number & Title

Document	Document Title
5252A	Revision of SEMI M57-1011 with Title Change To: Specifications for Silicon Annealed Wafers

II. Tally (Staff to fill in)

Voting Tally: As-cast tally after close of voting period

A minimum of 60% of the voting interests that have voting members within the technical committee must return votes. (Regulations ¶ 9.6.1)

	Return		Distribution		Return Rate	
Yellow	55	÷	91	=	60.4%	>=60%
Lilac & Others	8					
Total Vote	63					
Reject	0					
Accept	26					

A&R	🟪	Not approved
	Reason:	

III. Rejects

IV. Comments

Comment 1(Accept with comment)

Comment	**Referenced Section**	*TF/Committee to fill in if necessary	
	From	**Masanori Yoshise**	
	Comment	Accept with comment as Editorial error In Page 16, 1st reference at bottom of table is to be 10 instead of 8.	
	Discussion	Fix the foot note number 8 to 10.	
Action proposed	X	**The committee agreed to do one of the following actions.**	
		***No motion is required in this step.**	
			No further action was taken by the committee.
			Refer to the task force for more consideration.
			New Business
			Other
	Editorial Change		
		X	**Case 1: No vote in this section :**
			To be included and voted on in <u>§ 5. Summary of Editorial Changes</u>.
			Case 2: Voted in this section :
			Original section number and at least one full sentence are required in “FROM” and “TO” fields.
		1	**FROM: Section xxx**
			To: Section xxx
			Justification (If necessary)
		2	**FROM: Section xxx**
			To: Section xxx
			Justification (If necessary)
Motion by/2nd			
Vote			
A&R		**Not approved**	

	Reason:

Comment 2

Comment	Referenced Section	*TF/Committee to fill in if necessary
	From	**Murray Bullis (Materials and Metrologies)**
	Comment	Footnotes 8 and 9 on page 13 should not be repeated; instead footnote 8 should be replaced by a cross reference to footnote 6 and footnote 9 should be replaced by a crossreference to footnote 7. Footnotes 10 (incorrectly identified as footnote 8 in the footnote) and 11 on page 16 should not be repeated; instead footnote 10 should be replaced by a cross reference to footnote 6 and footnote 11 should be replaced by a cross reference to footnote 7.
	Discussion	Take out some repetition of footnotes and renumber them.

Action proposed	X	**The committee agreed to do one of the following actions.**	
		***No motion is required in this step.**	
			No further action was taken by the committee.
			Refer to the task force for more consideration.
			New Business
			Other
	Editorial Change		
		X	**Case 1: No vote in this section :**
			To be included and voted on in § 5. Summary of Editorial Changes.
			Case 2: Voted in this section :
			Original section number and at least one full sentence are required in “FROM” and “TO” fields.
		1	**FROM: Section xxx**
			To: Section xxx
			Justification (If necessary)
		2	**FROM: Section xxx** Attached file
			To: Section xxx
			Justification (If necessary)

Motion by/2nd		
Vote		
A&R	☐	**Not approved**
	Reason:	

Comment 3 (Abstain with comment)

Comment	**Referenced Section**	***TF/Committee to fill in if necessary**
	From	**Tetsuya Nakai (SUMCO)**
	Comment	It had better to delete #4 in Table R1-2, 2-6.1 Diameter (only 32nm Technology Generation) and Table R1-3, 2-6.1 Diameter, because we consider deleting 200mm wafer specifications for 32nm and future generations in SEMI documents such as M1, M62 and M49.
	Discussion	The Task Force will take it as new business.

Action proposed	X	**The committee agreed to do one of the following actions.**	
		***No motion is required in this step.**	
		☐	No further action was taken by the committee.
		☐	Refer to the task force for more consideration.
		X	New Business
		☐	Other
	Editorial Change		
		☐	**Case 1: No vote in this section :**
			To be included and voted on in § 5. Summary of Editorial Changes.
		☐	**Case 2: Voted in this section :**
			Original section number and at least one full sentence are required in "FROM" and "TO" fields.
		1	**FROM: Section xxx**
			To: Section xxx
			Justification (If necessary)
		2	**FROM: Section xxx**
			To: Section xxx

☐ ▨ ☐	**Justification** (If necessary)
Motion by/2nd	Ryuji Takeda (Covalent Silicon) / Takao Takenaka (Takenaka Consulant)
Vote	Motion passed (or failed)
A&R	🟪 **Not approved**
	Reason:

V. Summary of Editorial Changes

Note: Original section number and at least one full sentence are required in "FROM" and "TO" fields.

1	**FROM: Footnote 8** 8 The development of "Sample preparation method for minority carrier diffusion length measurement in silicon annealed wafer by surface photovoltage method" (JEITA EM-3509) by JEITA Silicon Technologies Committee is hereby acknowledged.
	TO: ~~8 The development of "Sample preparation method for minority carrier diffusion length measurement in silicon annealed wafer by surface photovoltage method" (JEITA EM-3509) by JEITA Silicon Technologies Committee is hereby acknowledged.~~
	Justification: (If necessary) Duplicated sentence of Footnote 6.
2	**FROM: Footnote 9** 9 The development of "Test method for bulk micro defect density and denuded zone width in annealed silicon wafers" (JEITA EM-3508) by JEITA Silicon Technologies Committee is hereby acknowledged.
	TO: ~~9 The development of "Test method for bulk micro defect density and denuded zone width in annealed silicon wafers" (JEITA EM-3508) by JEITA Silicon Technologies Committee is hereby acknowledged.~~
	Justification: (If necessary) Duplicated sentence of Footnote 7.
3	**FROM: Footnote 11** 11 The development of "Test method for bulk micro defect density and denuded zone width in annealed silicon wafers" (JEITA EM-3508) by JEITA Silicon Technologies Committee is hereby acknowledged.
	TO: ~~11 The development of "Test method for bulk micro defect density and denuded zone width in annealed silicon wafers" (JEITA EM-3508) by JEITA Silicon Technologies Committee is hereby acknowledged.~~
	Justification: (If necessary) Duplicated sentence of Footnote 7.
Motion	To approve the above editorial changes
Motion by/2nd by	Ryuji Takeda (Covalent Silicon) / Takao Takenaka (Takenaka Consultant)
Discussion	None

Vote	10-0 Motion passed	
A&R		**Not approved**
	Reason:	

VI. Approval Conditions Check

APPROVAL CONDITION 1: All negatives have been discussed and were withdrawn, found not related, or not persuasive. (Regulations ¶ 9.6.2)

APPROVAL CONDITION 2: At least 90% of the sum of the valid accept and reject votes must be accept. (Regulations ¶ 9.6.3)

Note: if both approval conditions are not satisfied, the document fails.

		Accepts		(Accepts + Valid			
Approval Rate	=	**26**	/	**26**	=	**100.0%**	**>=90%**

A&R		**Not approved**
	Reason:	

VII. Safety Check

See § 14 of the Regulations for further information

Motion:	X	This is not a Safety Document: when all safety-related information is removed, the document is still technically sound and complete.	
		This is a Safety Document: when all safety-related information is removed, the document is not technically sound and complete.	
			Safety Checklist (Regulations ¶ 14.3) is complete and has been included with the document throughout the balloting process.
Motion by/2nd by	Ryuji Takeda (Covalent Silicon)/Takao Takenaka (Takenaka Consultant)		
Discussion	None		
Vote	10-0 Motion passed		
A&R		**Not approved**	
	Reason:		

VIII. Intellectual Property Check

Note: This ballot may be all or part of a Standard or Safety Guideline. This IP check applies to the entire Standard or Safety Guideline. See § 15 of the Regulations for further information

X	The meeting chair asked those present in person or by electronic link, if they were aware of any potentially material patented technology or copyrighted items* in the Standard or Guideline.			
	X	No potentially material patented technology or copyrighted items are known		**GO TO SECTION IX**
		Potentially material patented technology or copyrighted items are known but a Letter of Assurance (LOA) or copyright release for such material has been obtained or presented to the committee.		**GO TO SECTION IX**
		Potentially material patented technology or copyrighted items are known but an LOA or copyright release for some of the material(s) has NOT been obtained or presented to the committee		
	MOTION		Ask ISC for special permission to publish	
			Quit activity	
			Wait for LOA for patented technology or release of copyrighted items.	
	Motion by/2nd by			
	Discussion			
	Vote			
	Final Action		Motion Passed	
			Motion Failed	
A&R		**Not approved**		
	Reason:			

* Note: Such potentially material patented technology or copyrighted items might have become known since the Standard or Safety Guideline was last reviewed, or might become relevant due to this ballot.

IX. Action for this document

Motion	X	This document passed committee review as balloted and will be forwarded to the A&R for procedural review.
		This document passed committee review with editorial changes and will be forwarded to the A&R for procedural review.
		This document failed committee review and will be returned to the task force for rework.
		This document failed committee review and work will be discontinued.

Motion by/2nd by	Ryuji Takeda (Covalent Silicon)/Takao Takenaka (Takenaka Consultant)	
Discussion	None	
Vote	10-0	
Final Action	X	Motion passed
		Motion failed
A&R		**Approved**
		Not approved
	Reason:	